

291-626



**STH4N90
STH4N90FI**

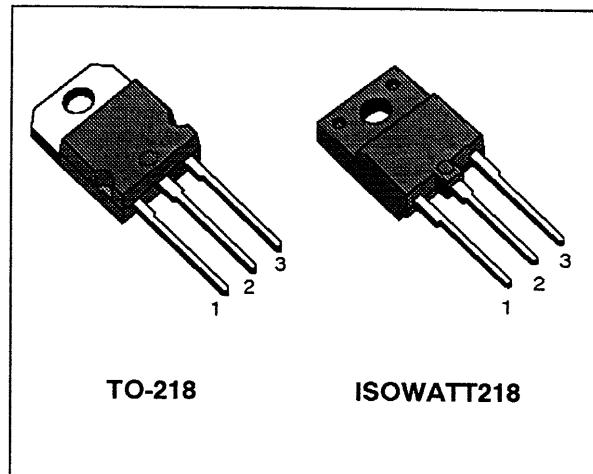
N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

TYPE	V _{DSS}	R _{DS(on)}	I _D
STH4N90	900 V	< 3.2 Ω	4.2 A
STH4N90FI	900 V	< 3.2 Ω	2.7 A

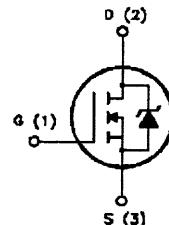
- TYPICAL R_{DS(on)} = 2.9 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100 °C
- LOW INPUT CAPACITANCE
- LOW GATE CHARGE
- APPLICATION ORIENTED CHARACTERIZATION

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- CONSUMER AND INDUSTRIAL LIGHTING
- DC-AC INVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLY (UPS)



INTERNAL SCHEMATIC DIAGRAM



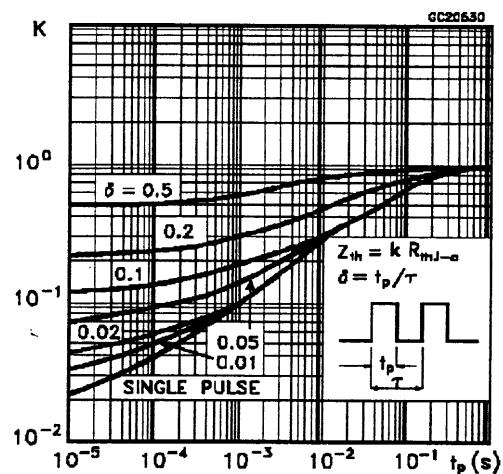
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STH4N90	STH4N90FI	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	900	—	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	900	—	V
V _{GS}	Gate-source Voltage	± 20	—	V
I _D	Drain Current (continuous) at T _c = 25 °C	4.2	2.7	A
I _D	Drain Current (continuous) at T _c = 100 °C	2.6	1.6	A
I _{DM(*)}	Drain Current (pulsed)	16	16	A
P _{tot}	Total Dissipation at T _c = 25 °C	125	55	W
	Derating Factor	1	0.44	W/°C
V _{ISO}	Insulation Withstand Voltage (DC)	—	4000	V
T _{stg}	Storage Temperature	-65 to 150		°C
T _j	Max. Operating Junction Temperature	150		°C

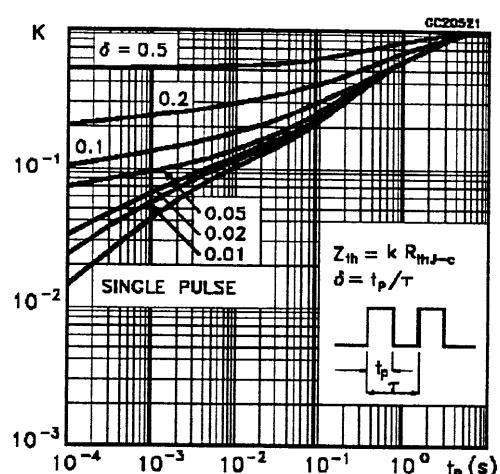
(*) Pulse width limited by safe operating area

STH4N90/FI

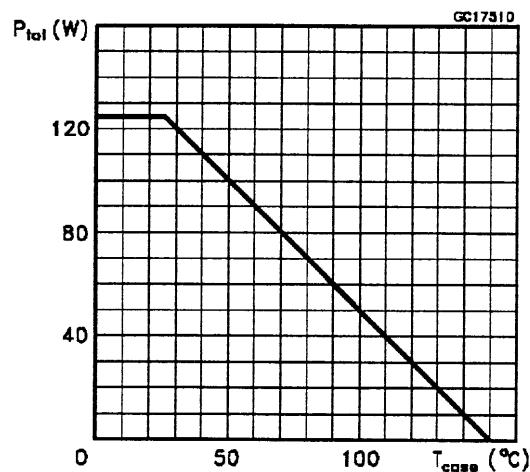
Thermal Impedance For TO-218



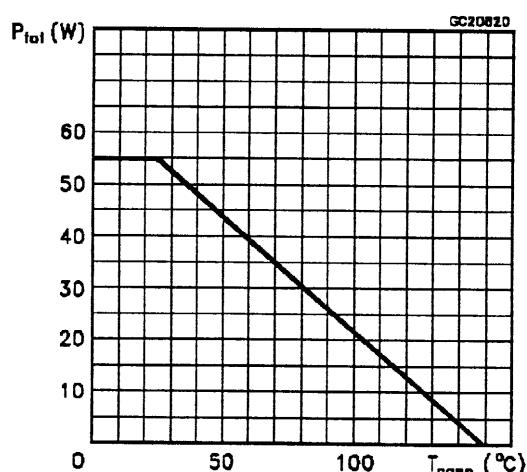
Thermal Impedance For ISOWATT218



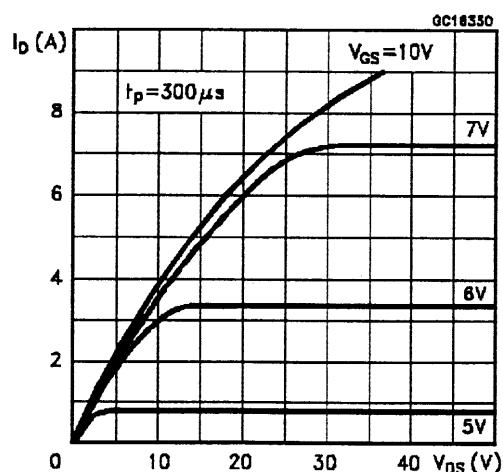
Derating Curve For TO-218



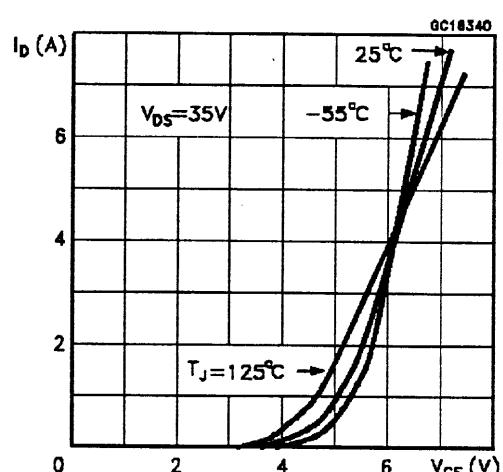
Derating Curve For ISOWATT218



Output Characteristics

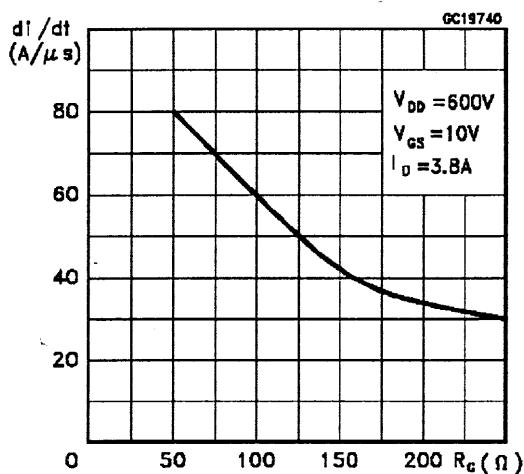


Transfer Characteristics

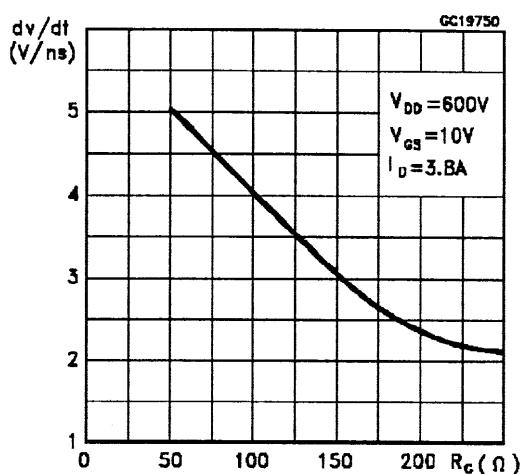


STH4N90/FI

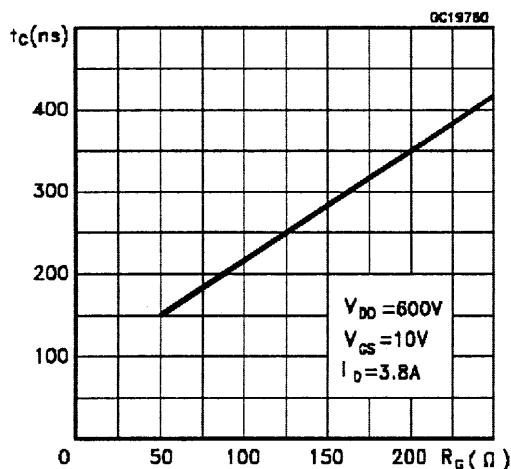
Turn-on Current Slope



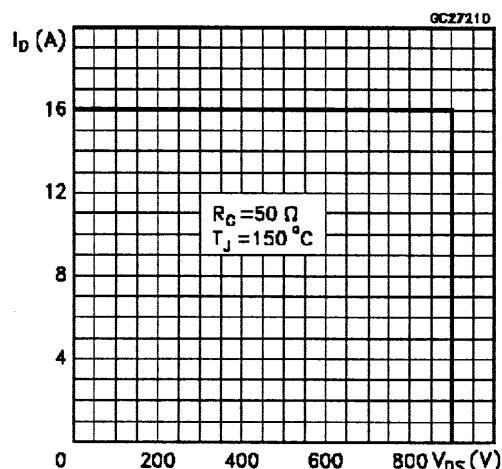
Turn-off Drain-source Voltage Slope



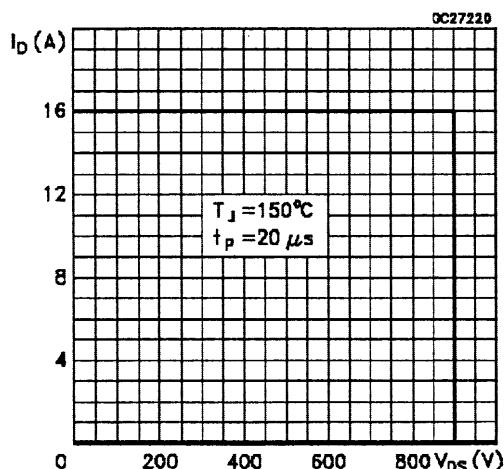
Cross-over Time



Switching Safe Operating Area



Accidental Overload Area



Source-drain Diode Forward Characteristics

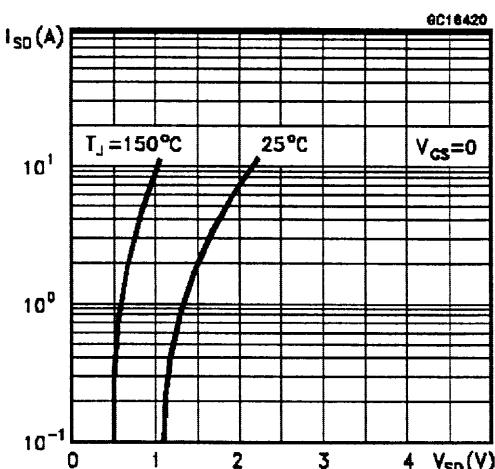
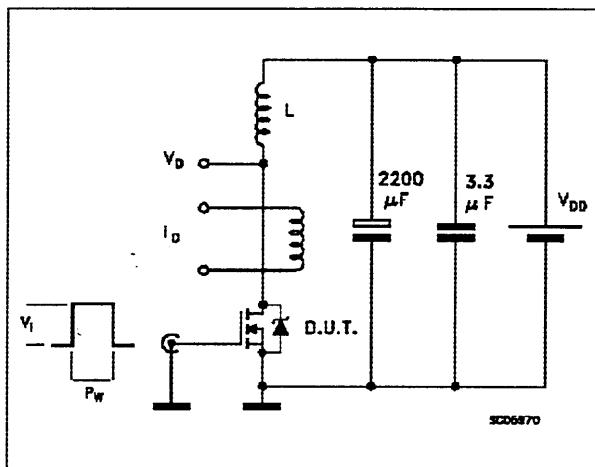
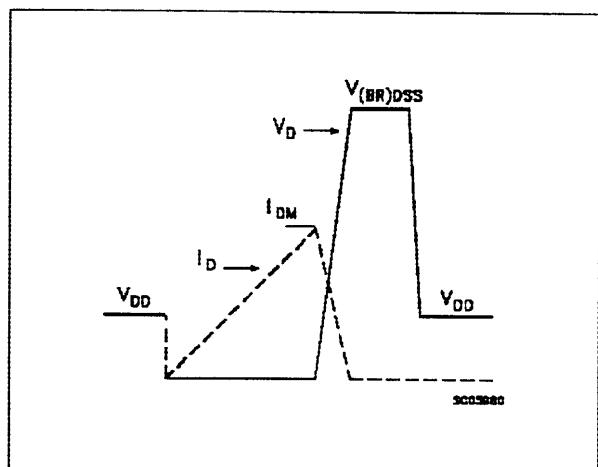
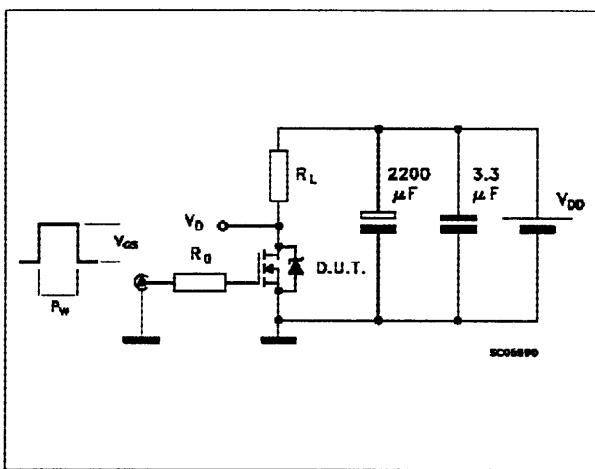
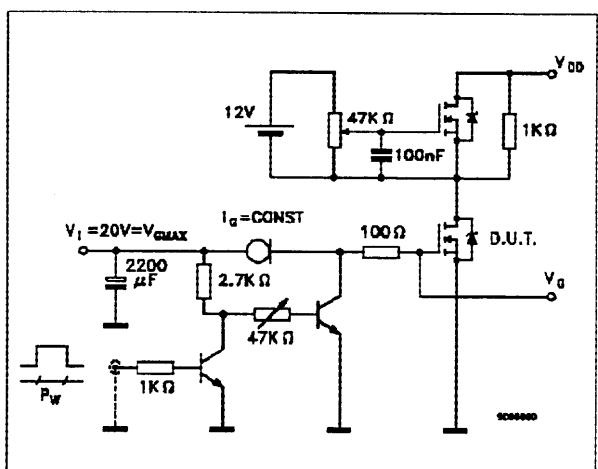
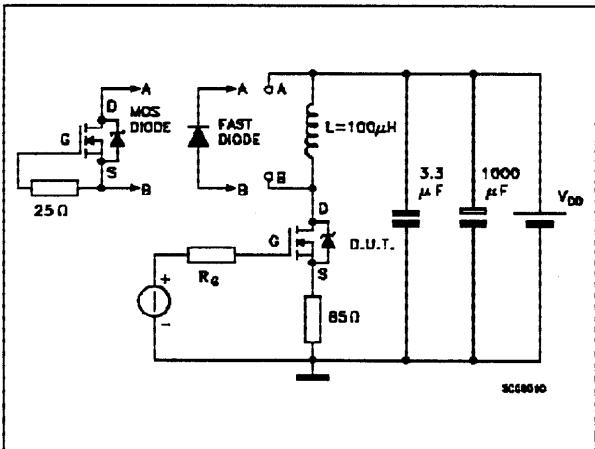
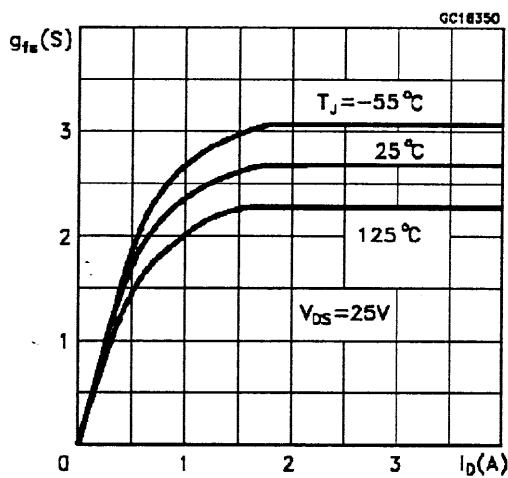
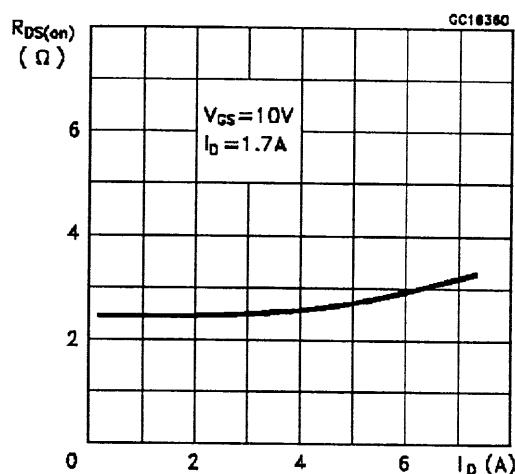


Fig. 1: Unclamped Inductive Load Test Circuits**Fig. 2:** Unclamped Inductive Waveforms**Fig. 3:** Switching Times Test Circuits For Resistive Load**Fig. 4:** Gate Charge Test Circuit**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time

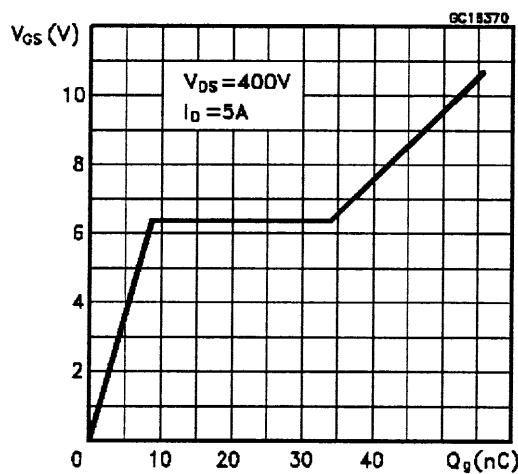
Transconductance



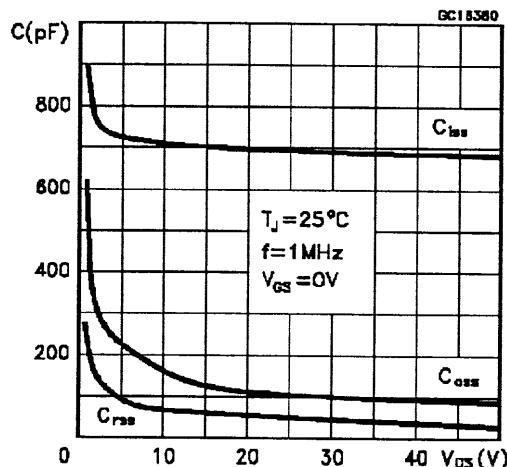
Static Drain-source On Resistance



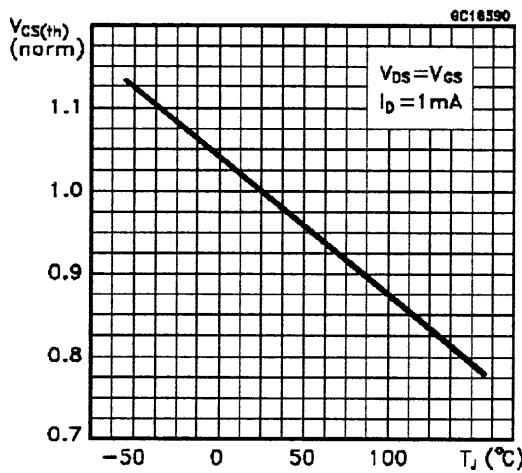
Gate Charge vs Gate-source Voltage



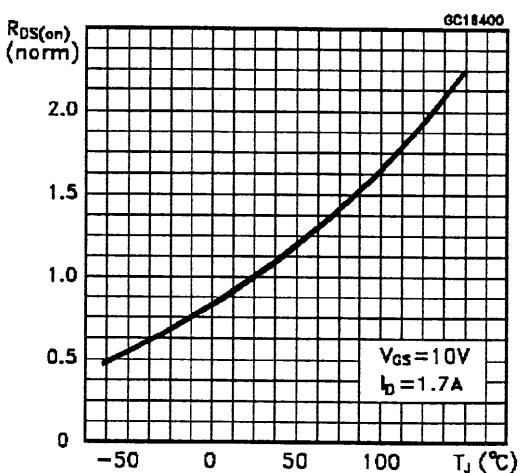
Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature



Normalized On Resistance vs Temperature



ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Time Rise Time	$V_{DD} = 30 \text{ V}$ $I_D = 2.3 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 3)		65 150	90 200	ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 600 \text{ V}$ $I_D = 3.8 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5)		80	110	A/ μs
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 400 \text{ V}$ $I_D = 5 \text{ A}$ $V_{GS} = 10 \text{ V}$		55 8 26	70	nC nC nC

SWITCHING OFF

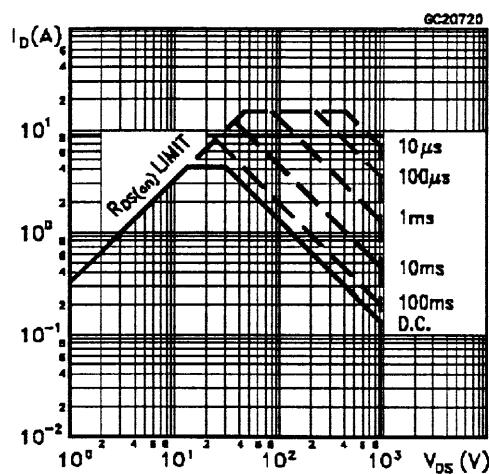
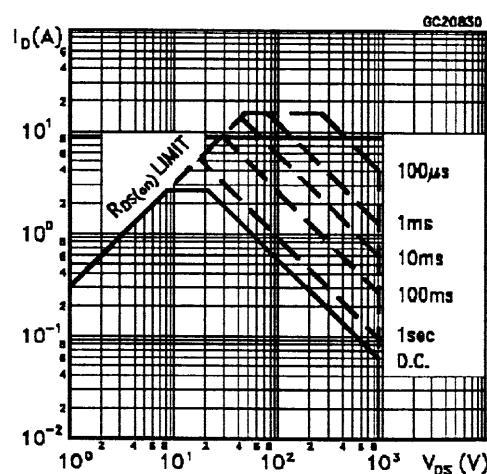
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(voff)}$ t_f t_c	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 600 \text{ V}$ $I_D = 3.8 \text{ A}$ $R_G = 50 \Omega$ $V_{GS} = 10 \text{ V}$ (see test circuit, figure 5)		110 140 150	145 190 200	ns ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(•)$	Source-drain Current Source-drain Current (pulsed)				4.2 16	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 4.2 \text{ A}$ $V_{GS} = 0$			2	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 3.8 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_R = 100 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, figure 5)		500 4.3 17		ns μC A

(•) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(*) Pulse width limited by safe operating area

Safe Operating Areas For TO-218**Safe Operating Areas For ISOWATT218**

STH4N90/FI

THERMAL DATA

		TO-218	ISOWATT218	
R _{thj-case}	Thermal Resistance Junction-case	Max	1	2.27 °C/W
R _{thj-amb}	Thermal Resistance Junction-ambient	Max	30	°C/W
R _{thc-sink}	Thermal Resistance Case-sink	Typ	0.1	°C/W
T _j	Maximum Lead Temperature For Soldering Purpose		300	°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max, δ < 1%)	4.2	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	230	mJ
E _{AR}	Repetitive Avalanche Energy (pulse width limited by T _j max, δ < 1%)	10	mJ
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (T _c = 100 °C, pulse width limited by T _j max, δ < 1%)	2.6	A

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

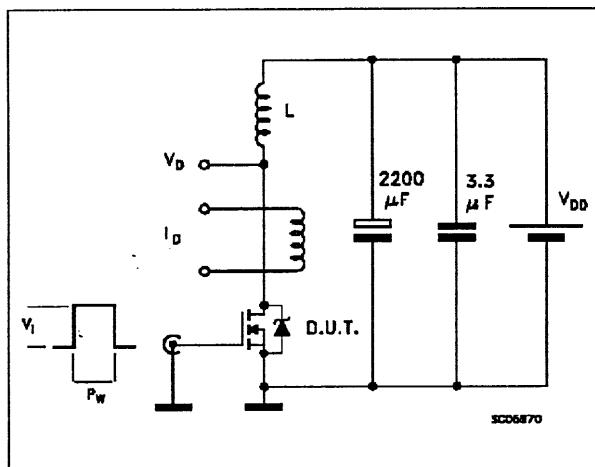
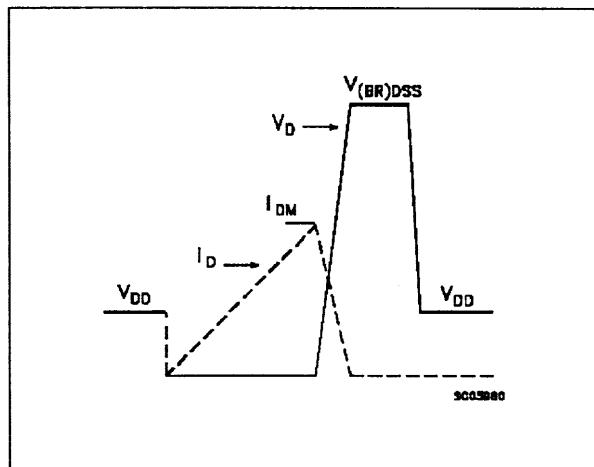
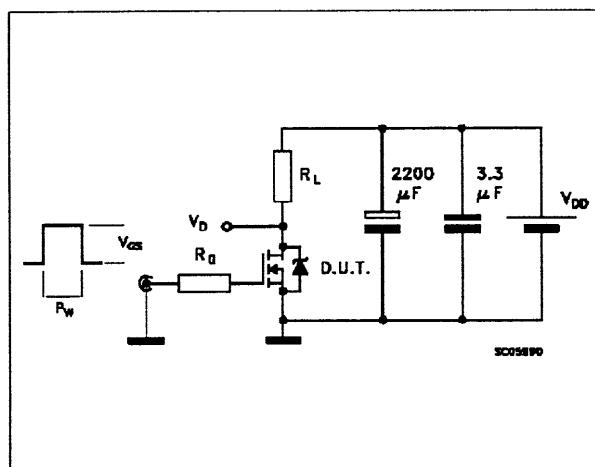
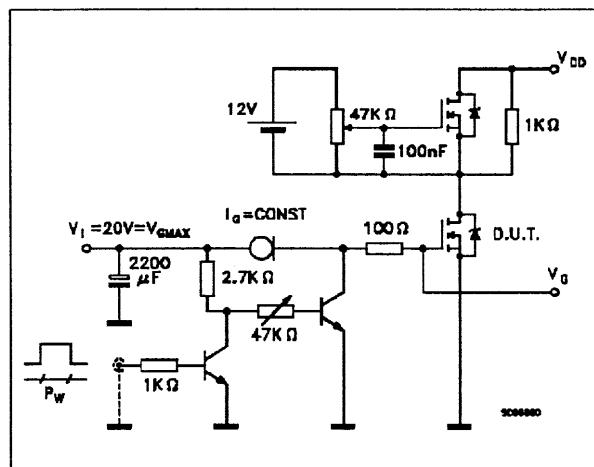
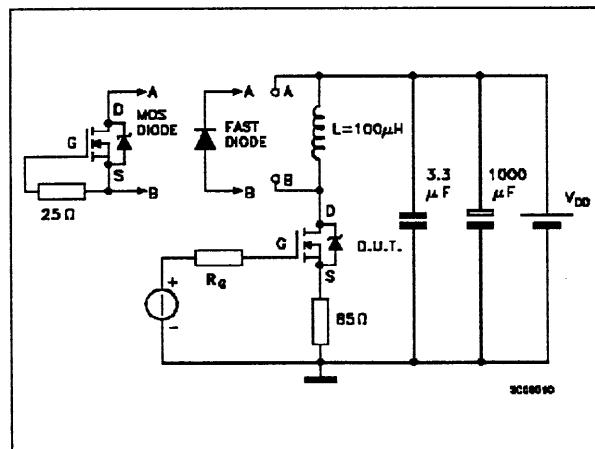
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	900			V
I _{oss}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating × 0.8 T _c = 125 °C			250 1000	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{Gs(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	2	3	4	V
R _{Ds(on)}	Static Drain-source On Resistance	V _{GS} = 10V I _D = 1.7 A V _{GS} = 10V I _D = 1.7 A T _c = 100 °C		2.9	3.2 6.4	Ω Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} × R _{Ds(on)max} V _{GS} = 10 V	4.2			A

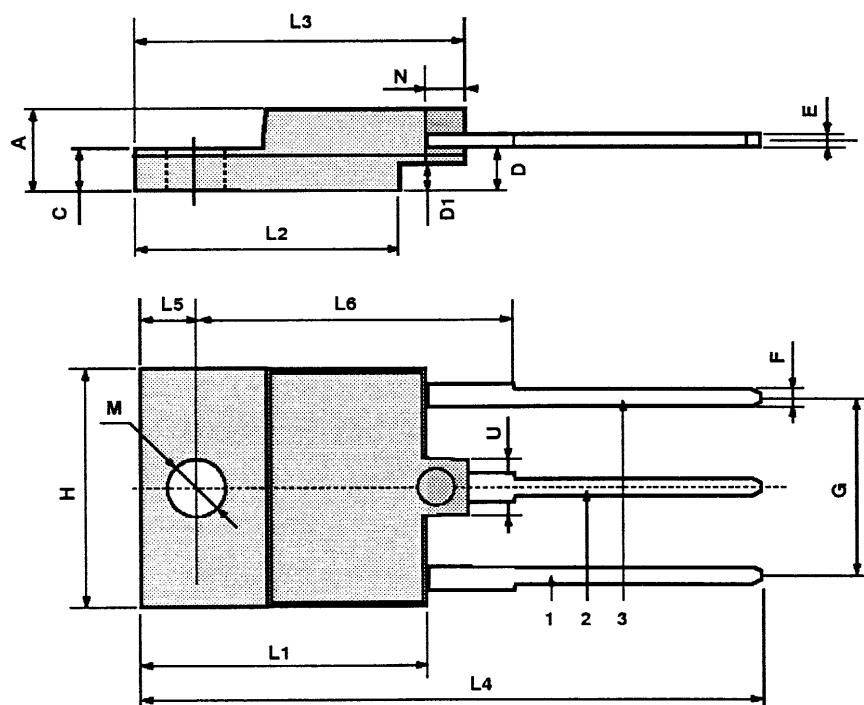
DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} × R _{Ds(on)max} I _D = 1.7 A	1			S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0			1100 150 55	pF pF pF

Fig. 1: Unclamped Inductive Load Test Circuits**Fig. 2: Unclamped Inductive Waveforms****Fig. 3: Switching Times Test Circuits For Resistive Load****Fig. 4: Gate Charge Test Circuit****Fig. 5: Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time**

ISOWATT218 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	5.35		5.65	0.210		0.222
C	3.3		3.8	0.130		0.149
D	2.9		3.1	0.114		0.122
D1	1.88		2.08	0.074		0.081
E	0.45		1	0.017		0.039
F	1.05		1.25	0.041		0.049
G	10.8		11.2	0.425		0.441
H	15.8		16.2	0.622		0.637
L1	20.8		21.2	0.818		0.834
L2	19.1		19.9	0.752		0.783
L3	22.8		23.6	0.897		0.929
L4	40.5		42.5	1.594		1.673
L5	4.85		5.25	0.190		0.206
L6	20.25		20.75	0.797		0.817
M	3.5		3.7	0.137		0.145
N	2.1		2.3	0.082		0.090
U		4.6			0.181	



TO-218 (SOT-93) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.7		4.9	0.185		0.193
C	1.17		1.37	0.046		0.054
D		2.5			0.098	
E	0.5		0.78	0.019		0.030
F	1.1		1.3	0.043		0.051
G	10.8		11.1	0.425		0.437
H	14.7		15.2	0.578		0.598
L ₂	-		16.2	-		0.637
L ₃		18			0.708	
L ₅	3.95		4.15	0.155		0.163
L ₆		31			1.220	
R	-		12.2	-		0.480
Ø	4		4.1	0.157		0.161

